

Quad 2-Input NAND Schmitt Trigger

MM74HC132

General Description

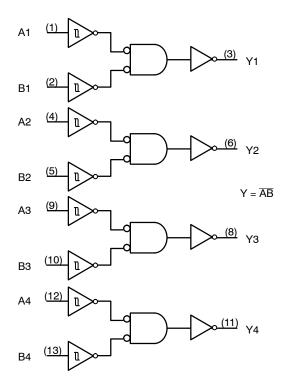
The MM74HC132 utilizes advanced silicon-gate CMOS technology to achieve the low power dissipation and high noise immunity of standard CMOS, as well as the capability to drive 10 LS-TTL loads.

The 74HC logic family is functionally and pinout compatible with the standard 74LS logic family. All inputs are protected from damage due to static discharge by internal diode clamps to V_{CC} and ground.

Features

- Typical Propagation Delay: 12 ns
- Wide Power Supply Range: 2 V 6 V
- Low Quiescent Current: 40 μA maximum (74HC Series)
- Low Input Current: 1 μA Maximum
- Fanout of 10 LS-TTL Loads
- Typical Hysteresis Voltage: 0.9 V at $V_{CC} = 4.5 \text{ V}$
- These Devices are Pb-Free, Halide Free and are RoHS Compliant

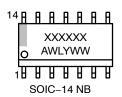
Logic Diagram

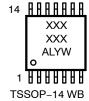






MARKING DIAGRAM

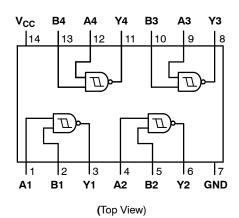




XXX = Specific Device Code A = Assembly Location

WL, L = Wafer Lot Y = Year WW, W = Work Week

CONNECTION DIAGRAM Pin Assignments for SOIC and TSSOP



ORDERING INFORMATION

See detailed ordering and shipping information on page 4 of this data sheet

MM74HC132

ABSOLUTE MAXIMUM RATINGS (Note 1)

Symbol	Parameter	Rating	Units
V _{CC}	Supply Voltage	-0.5 to +6.5	V
V _{IN}	DC Input Voltage	-0.5 to V _{CC} + 0.5	V
V _{OUT}	DC Output Voltage	-0.5 to V _{CC} + 0.5	V
I _{IK} , I _{OK}	Clamp Diode Current	±20	mA
I _{OUT}	DC Output Current, per Pin	±25	mA
I _{CC}	DC V _{CC} or GND Current, per Pin	±50	mA
T _{STG}	Storage Temperature Range	−65 to +150	°C
P _D	Power Dissipation SOIC TSSOP	1077 833	mW
T_L	Lead Temperature (Soldering 10 Seconds)	260	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. Unless otherwise specified all voltages are referenced to ground.

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter	Min	Max	Unit
V _{CC}	Supply Voltage	2	6	V
V _{IN} , V _{OUT}	DC Input or Output Voltage	0	V _{CC}	V
T _A	Operating Temperature Range	- 55	+125	°C

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

MM74HC132

DC CHARACTERISTICS (Note 2)

				T _A =	25°C	T _A = -40°C to 85°C	T _A = -55°C to 125°C	
Symbol	Parameter	V _{CC} (V)	Conditions	Тур		auaranteed Li	mits	Unit
V _{T+} min	Positive Going Threshold Voltage	2.0		-	1.0	1.0	1.0	V
		4.5		_	2.0	2.0	2.0	
		6.0		_	3.0	3.0	3.0	
V _{T+} max	1	2.0		-	1.5	1.5	1.5	V
		4.5		_	3.15	3.15	3.15	
		6.0		_	4.2	4.2	4.2	
V _T min	Negative Going Threshold Voltage	2.0		-	0.3	0.3	0.3	V
		4.5		_	0.9	0.9	0.9	
		6.0		_	1.2	1.2	1.2	
V _{T-} max	1	2.0		-	1.0	1.0	1.0	V
		4.5		_	2.2	2.2	2.2	
		6.0		_	3.0	3.0	3.0	
V _H min	Hysteresis Voltage	2.0		-	0.2	0.2	0.2	V
		4.5		_	0.4	0.4	0.4	
		6.0		_	0.5	0.5	0.5	
V _H max	1	2.0		-	1.0	1.0	1.0	V
		4.5		_	1.4	1.4	1.4	
		6.0		_	1.5	1.5	1.5	
V _{OH}	Minimum HIGH Level Output	2.0	$V_{IN} = V_{IH}$ or V_{IL} ,	2.0	1.9	1.9	1.9	V
	Voltage	4.5	I _{OUT} ≤ 20 μA	4.5	4.4	4.4	4.4	
		6.0		6.0	5.9	5.9	5.9	
		4.5	$V_{IN} = V_{IH} \text{ or } V_{IL},$ $ I_{OUT} \le 4.0 \text{ mA}$	4.2	3.98	3.84	3.7	
		6.0	$V_{IN} = V_{IH} \text{ or } V_{IL},$ $ I_{OUT} \le 5.2 \text{ mA}$	5.7	5.48	5.34	5.2	
V _{OL}	Maximum LOW Level Output	2.0	$V_{IN} = V_{IH}$ or V_{IL} ,	0	0.1	0.1	0.1	V
	Voltage	4.5	I _{OUT} ≤ 20 μA	0	0.1	0.1	0.1	
		6.0		0	0.1	0.1	0.1	
		4.5	$V_{IN} = V_{IH} \text{ or } V_{IL},$ $ I_{OUT} \le 4.0 \text{ mA}$	0.2	0.26	0.33	0.4	
		6.0	$V_{IN} = V_{IH} \text{ or } V_{IL},$ $ I_{OUT} \le 5.2 \text{ mA}$	0.2	0.26	0.33	0.4	
I _{IN}	Maximum Input Current	6.0	V _{IN} = V _{CC} or GND	-	±0.1	±1.0	±1.0	μΑ
I _{CC}	Maximum Quiescent Supply Current	6.0	$V_{IN} = V_{CC}$ or GND, $I_{OUT} = 0 \mu A$	-	2.0	20	40	μΑ

^{2.} For a power supply of 5 V \pm 10% the worst case output voltages (V_{OH}, and V_{OL}) occur for HC at 4.5 V. Thus the 4.5 V values should be used when designing with this supply. Worst case V_{IH} and V_{IL} occur at V_{CC} = 5.5 V and 4.5 V respectively. (The V_{IH} value at 5.5 V is 3.85 V.) The worst case leakage current (I_{IN}, I_{CC}, and I_{OZ}) occur for CMOS at the higher voltage and so the 6.0 V values should be used.

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AC CHARACTERISTICS (V $_{CC}$ = 5 V, T_A = 25°C, C_L = 15 pF, t_r = t_f = 6 ns)

Symbol	Parameter	Conditions	Тур	Guaranteed Limit	Unit
t_{PHL} , t_{PLH}	Maximum Propagation Delay		12	20	ns

AC CHARACTERISTICS (V_{CC} = 2.0 V to 6.0 V, C_L = 50 pF, t_r = t_f = 6 ns (unless otherwise specified))

				T _A =	25°C	T _A = -40°C to 85°C	T _A = -55°C to 125°C	
Symbol	Parameter	V _{CC} (V)	Conditions	Тур	G	iuaranteed Li	mits	Unit
t _{PHL} , t _{PLH}	Maximum Propagation Delay	2.0		63	125	158	186	ns
		4.5		13	25	32	37	
		6.0		11	21	27	32	
t _{TLH} , t _{THL}	Maximum Output Rise and Fall Time	2.0		30	75	95	110	ns
		4.5		8	15	19	22	
		6.0		7	13	16	19	
C _{PD}	Power Dissipation Capacitance (Note 3)		(per gate)	130	-		-	pF
C _{IN}	Maximum Input Capacitance			-	5	10	10	pF

^{3.} C_{PD} determines the no load dynamic power consumption, $P_D = C_{PD} \ V_{CC}^2 \ f + I_{CC} \ V_{CC}$, and the no load dynamic current consumption, $I_S = C_{PD} \ V_{CC} \ f + I_{CC}$.

ORDERING INFORMATION

Part Number	Markiing	Package	Shipping [†]
MM74HC132M	HC132A	SOIC-14, Case 751A	55 Units / Tube
MM74HC132MX	HC132A	SOIC-14, Case 751A	2500 / Tape & Reel
MM74HC132MTC	HC 132A	TSSOP-14, Case 948G	96 Units / Tube
MM74HC132MTCX	HC 132A	TSSOP-14, Case 948G	2500 / Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

NOTE: Device also available in Tape and Reel. Specify by appending suffix letter "X" to the ordering number.

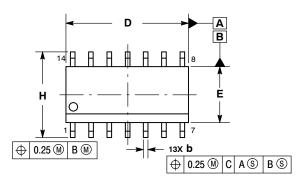


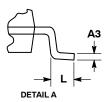


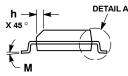
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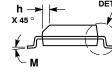
SOIC-14 NB CASE 751A-03 ISSUE L

DATE 03 FEB 2016





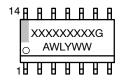




- NOTES:
 1. DIMENSIONING AND TOLERANCING PER
 - ASME Y14.5M, 1994.
 CONTROLLING DIMENSION: MILLIMETERS.
- DIMENSION b DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE PROTRUSION SHALL BE 0.13 TOTAL IN EXCESS OF AT
- MAXIMUM MATERIAL CONDITION.
 DIMENSIONS D AND E DO NOT INCLUDE MOLD PROTRUSIONS.
- 5. MAXIMUM MOLD PROTRUSION 0.15 PER SIDE

	MILLIM	IETERS	INCHES	
DIM	MIN	MAX	MIN	MAX
Α	1.35	1.75	0.054	0.068
A1	0.10	0.25	0.004	0.010
АЗ	0.19	0.25	0.008	0.010
b	0.35	0.49	0.014	0.019
D	8.55	8.75	0.337	0.344
Е	3.80	4.00	0.150	0.157
е	1.27	BSC	0.050 BSC	
Н	5.80	6.20	0.228	0.244
h	0.25	0.50	0.010	0.019
L	0.40	1.25	0.016	0.049
M	0 °	7°	0 °	7°

GENERIC MARKING DIAGRAM*

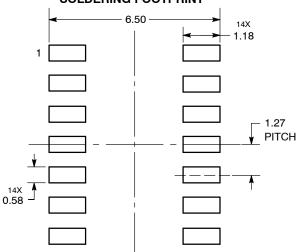


XXXXX = Specific Device Code Α = Assembly Location

WL = Wafer Lot Υ = Year WW = Work Week = Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "■", may or may not be present. Some products may not follow the Generic Marking.

SOLDERING FOOTPRINT*



DIMENSIONS: MILLIMETERS

C SEATING PLANE

STYLES ON PAGE 2

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DESCRIPTION:	SOIC-14 NB		PAGE 1 OF 2

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^{*}For additional information on our Pb-Free strategy and soldering details, please download the onsemi Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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DATE 03 FEB 2016

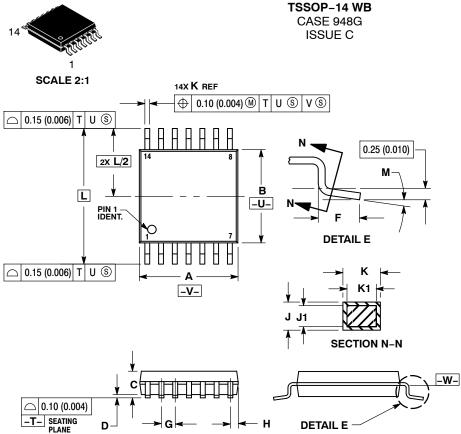
STYLE 1: PIN 1. COMMON CATHODE 2. ANODE/CATHODE 3. ANODE/CATHODE 4. NO CONNECTION 5. ANODE/CATHODE 6. NO CONNECTION 7. ANODE/CATHODE 8. ANODE/CATHODE 9. ANODE/CATHODE 10. NO CONNECTION 11. ANODE/CATHODE 12. ANODE/CATHODE 13. NO CONNECTION 14. COMMON ANODE	STYLE 2: CANCELLED	STYLE 3: PIN 1. NO CONNECTION 2. ANODE 3. ANODE 4. NO CONNECTION 5. ANODE 6. NO CONNECTION 7. ANODE 8. ANODE 9. ANODE 10. NO CONNECTION 11. ANODE 12. ANODE 13. NO CONNECTION 14. COMMON CATHODE	STYLE 4: PIN 1. NO CONNECTION 2. CATHODE 3. CATHODE 4. NO CONNECTION 5. CATHODE 6. NO CONNECTION 7. CATHODE 8. CATHODE 9. CATHODE 10. NO CONNECTION 11. CATHODE 12. CATHODE 13. NO CONNECTION 14. COMMON ANODE
STYLE 5: PIN 1. COMMON CATHODE 2. ANODE/CATHODE 3. ANODE/CATHODE 4. ANODE/CATHODE 5. ANODE/CATHODE 6. NO CONNECTION 7. COMMON ANODE 8. COMMON CATHODE 9. ANODE/CATHODE 10. ANODE/CATHODE 11. ANODE/CATHODE 12. ANODE/CATHODE 13. NO CONNECTION 14. COMMON ANODE	STYLE 6: PIN 1. CATHODE 2. CATHODE 3. CATHODE 4. CATHODE 5. CATHODE 6. CATHODE 7. CATHODE 8. ANODE 9. ANODE 10. ANODE 11. ANODE 12. ANODE 13. ANODE 14. ANODE	STYLE 7: PIN 1. ANODE/CATHODE 2. COMMON ANODE 3. COMMON CATHODE 4. ANODE/CATHODE 6. ANODE/CATHODE 6. ANODE/CATHODE 7. ANODE/CATHODE 8. ANODE/CATHODE 9. ANODE/CATHODE 10. ANODE/CATHODE 11. COMMON CATHODE 12. COMMON ANODE 13. ANODE/CATHODE 14. ANODE/CATHODE	STYLE 8: PIN 1. COMMON CATHODE 2. ANODE/CATHODE 3. ANODE/CATHODE 4. NO CONNECTION 5. ANODE/CATHODE 6. ANODE/CATHODE 7. COMMON ANODE 8. COMMON ANODE 9. ANODE/CATHODE 10. ANODE/CATHODE 11. NO CONNECTION 12. ANODE/CATHODE 13. ANODE/CATHODE 14. COMMON CATHODE

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DESCRIPTION:	SOIC-14 NB		PAGE 2 OF 2

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DATE 17 FEB 2016





- NOTES.

 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.

 2. CONTROLLING DIMENSION: MILLIMETER.

 3. DIMENSION A DOES NOT INCLUDE MOLD
- FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
 DIMENSION B DOES NOT INCLUDE
- INTERLEAD FLASH OR PROTRUSION.
 INTERLEAD FLASH OR PROTRUSION SHALL
- INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.

 DIMENSION K DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE K DIMENSION AT MAXIMUM MATERIAL CONDITION.

 TERMINAL NUMBERS ARE SHOWN FOR DEEEDENIC OMITY.
- REFERENCE ONLY.
 DIMENSION A AND B ARE TO BE
- DETERMINED AT DATUM PLANE -W-.

	MILLIN	IETERS	INC	HES
DIM	MIN	MAX	MIN	MAX
Α	4.90	5.10	0.193	0.200
В	4.30	4.50	0.169	0.177
С		1.20		0.047
D	0.05	0.15	0.002	0.006
F	0.50	0.75	0.020	0.030
G	0.65	BSC	0.026 BSC	
Н	0.50	0.60	0.020	0.024
J	0.09	0.20	0.004	0.008
J1	0.09	0.16	0.004	0.006
K	0.19	0.30	0.007	0.012
K1	0.19	0.25	0.007	0.010
L	6.40	BSC	0.252	BSC
М	0°	8 °	0 °	8 °

GENERIC MARKING DIAGRAM*



= Assembly Location

L = Wafer Lot = Year

= Work Week W = Pb-Free Package

(Note: Microdot may be in either location)

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "■", may or may not be present. Some products may not follow the Generic Marking.

RECOMMENDED SOLDERING FOOTPRINT*

-	7.06
1	
	-
	U 0.65 PITCH
↓ □	The state of the s
14X 0.36	
0.36 - 1.26	DIMENSIONS: MILLIMETERS

*For additional information on our Pb-Free strategy and soldering details, please download the onsemi Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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